

IMPROVED POLYTETRAFLUOROETHYLENE THIN FILM CHIP CARRIER
ABSTRACT

The present invention provides an organic chip carrier (10) particularly useful with flip chips, comprising an organic dielectric layer, a first layer of circuitry (25) disposed on the dielectric layer, an organic conformational coating (34) disposed over the first layer of dielectric (22) and the first layer of circuitry, and a layer of fine line circuitry (40) having line width of about 2.0 mil or less, preferably about 1.0 mil or less, preferably about 0.7 mil, and a space between lines of about 1.5 mil or less, preferably about 1.1 mil or less, disposed on the conformational layer. Preferably the dielectric layer is free of woven fiber glass. The conformational coating preferably has a dielectric constant of about 1.5 to about 3.5, and a percent planarization of greater than about 30%. The invention also relates to methods of making the dielectric coated chip carrier.

Fig. 1

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